SOLID STATE OPTRONICS



SDT800

DC Input
60V
Dual Photo-Transistor Optocoupler

Description

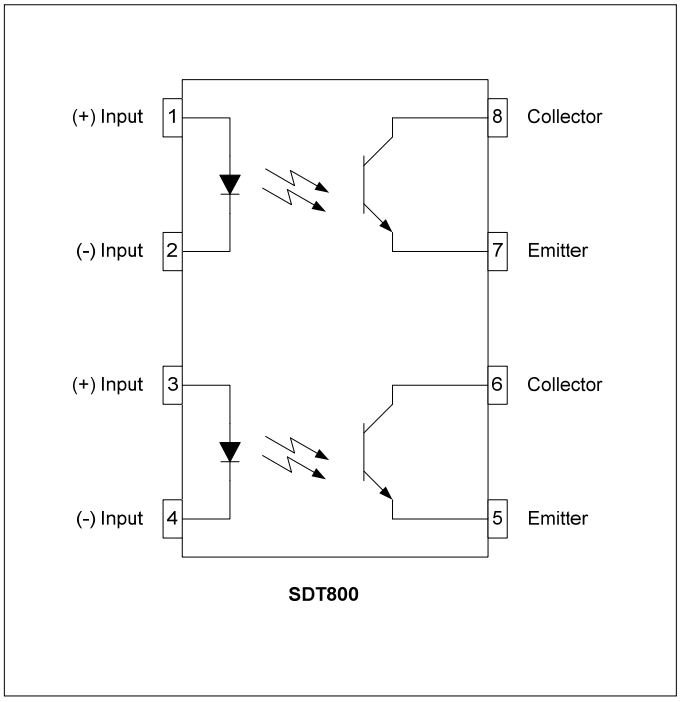
The SDT800 consists of two phototransistors, each optically coupled to a light emitting diode for DC input operation. Optical coupling between the input IR LED and output phototransistor allows for high isolation levels while maintaining low-level DC signal control capability. The SDT800 provides an optically isolated method of controlling many interface applications such as telecommunications, industrial control and instrumentation circuitry.

The SDT800 comes standard in a miniature 8 pin DIP package.

Applications

- Registers, Copiers, Automatic Vending Machines
- System Appliances, Measuring Instruments
- Computer Terminals, PLCs
- Telecommunication Equipment, Telephones
- Home Appliances
- Digital Logic Inputs
- Microprocessor Inputs
- Switching Power Supplies

Schematic Diagram



SDT800

Features

- V_{CEO} = 60V
- Small 8 pin DIP/SMD package
- Low input power consumption
- High stability
- CTR Range 50 – 600%
- High Isolation Voltage (5000V_{RMS})
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL:	File # E201932
VDE:	File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	-55 to +125°C
Operating Temperature	-40 to +100°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	6V
Input Power Dissipation[1]	40mW
Total Power Dissipation[1]	300mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature – IR Reflow (10sec)	260°C

NOTES

1. Power Dissipation per Channel

Ordering Information

Part Number	Description
SDT800	8 pin DIP, (50/Tube)
SDT800-H	0.40” (10.16mm) Lead Spacing (VDE0884)
SDT800-S	8 pin SMD, (50/Tube)
SDT800-STR	8 pin SMD, Tape and Reel (1000/Reel)

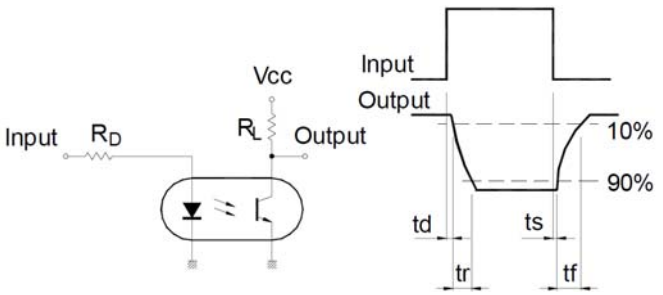
NOTE: Suffixes listed above are not included in marking on device for part number identification

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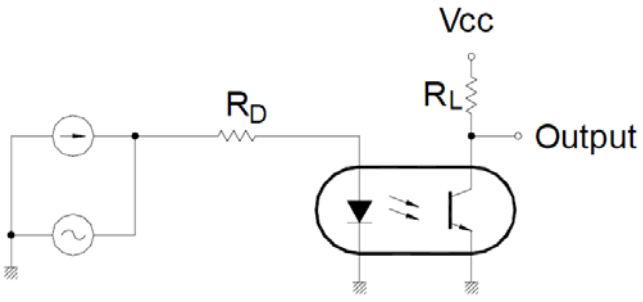
Electrical Characteristics, T_A = 25°C (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.2	1.4	V	I_F = 20mA
LED Reverse Voltage	BV_R	5	-	-	V	I_R = 10μA
Terminal Capacitance	C_t	-	30	250	pF	V=0, f=1KHz
Input Reverse Current	I_R	-	-	10	μA	V_R=4V
Output Specifications						
Collector-Emitter Voltage	V_{CEO}	60	-	-	V	I_C=10μA
Emitter-Collector Voltage	V_{COE}	6	-	-	V	I_E=10μA
Collector Dark Current	I_{CEO}	-	-	100	nA	V_{CE}=20V
Floating Capacitance	C_f	-	0.6	1.0	pF	V_{CE}=0, f=1MHz
Cut-Off Frequency	f_C	-	80	-	kHz	V_{CE}=5V, I_C=2mA, R_L=100Ω, -3dB
Saturation Voltage	$V_{CE(sat)}$	-	0.1	0.2	V	I_F=20mA, I_C=1mA
Coupled Specifications						
Rise Time	T_R	-	4.0	18.0	μS	I_C=2mA, V_{CC}=2V, R_L=100Ω
Fall Time	T_F	-	3.0	18.0	μS	I_C=2mA, V_{CC}=2V, R_L=100Ω
Current Transfer Ratio	CTR	50	-	600	%	I_F=5mA, V_{CE}=5V
CTR Classification (BINNING)						
- A		80	-	160	%	I_F=5mA, V_{CE}=5V
- B		130	-	260	%	I_F=5mA, V_{CE}=5V
- C		200	-	400	%	I_F=5mA, V_{CE}=5V
- D		300	-	600	%	I_F=5mA, V_{CE}=5V
- E		50	-	600	%	I_F=5mA, V_{CE}=5V
Isolation Specifications						
Isolation Voltage	V_{ISO}	5000	-	-	V_{RMS}	RH ≤ 50%, t=1min
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	V_{I-O} = 500V_{DC}

Test Circuit: *Response Time*



Test Circuit: *Frequency Response*



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SDT800 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 1: *Forward Current (I_F) vs. Temperature (°C)*

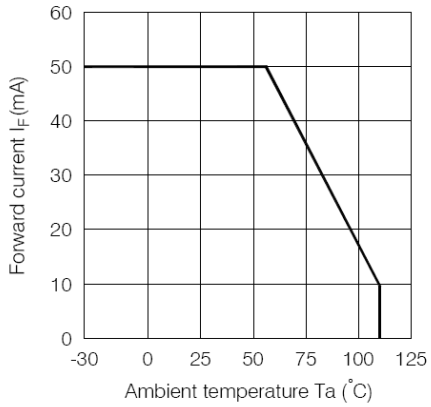


Figure 2: *Collector Power Dissipation (P_C) vs. Temperature (°C)*

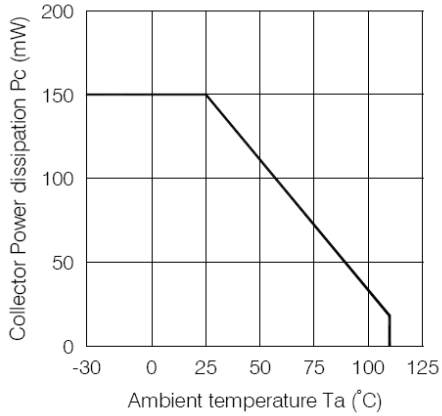


Figure 3: *Collector-Emitter Saturation Voltage ($V_{CE(SAT)}$) vs. Forward Current (I_F)*

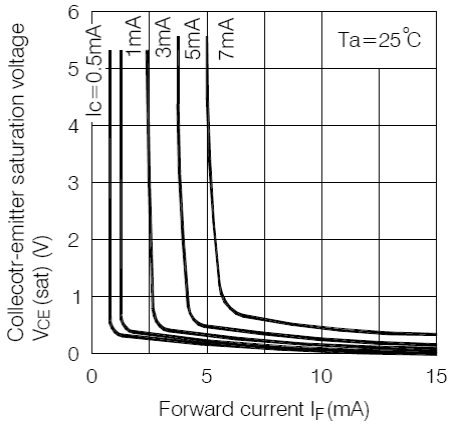


Figure 4: *Forward Current (I_F) vs. Forward Voltage (V_F)*

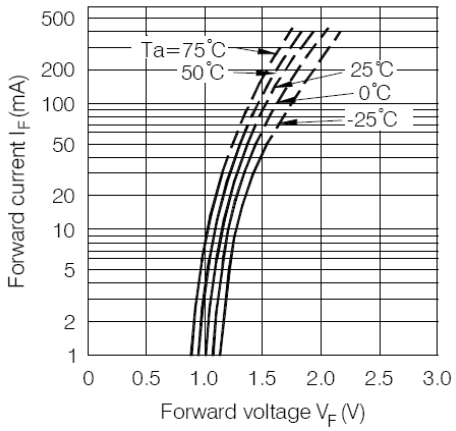


Figure 5: *Collector Current (I_C) vs. Collector-Emitter Voltage (V_{CE})*

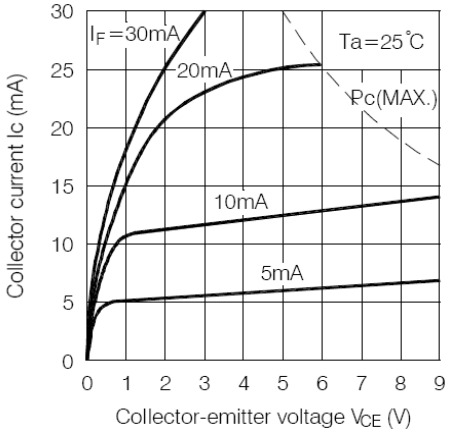
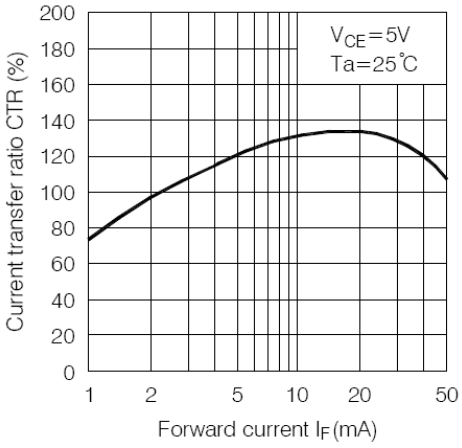


Figure 6: *Current Transfer Ratio (CTR) vs. Forward Current (I_F)*



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SDT800 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 7: *Relative CTR (%) vs. Temperature (°C)*

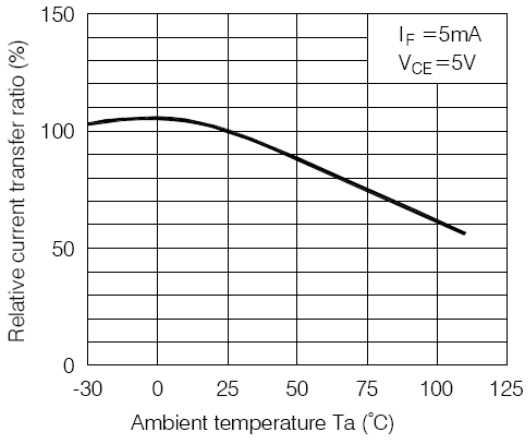


Figure 8: *Collector-Emitter Saturation Voltage ($V_{CE(SAT)}$) vs. Temperature (°C)*

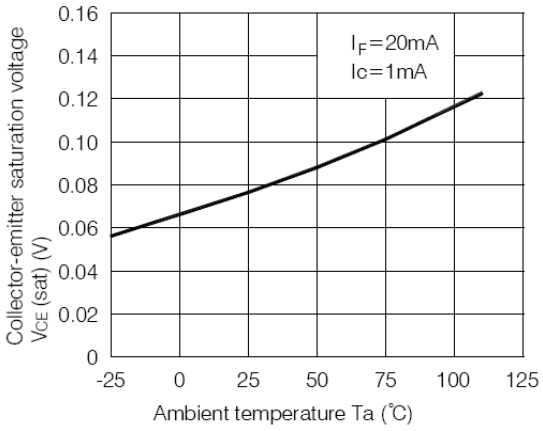


Figure 9: *Collector Dark Current (I_{CEO}) vs. Temperature (°C)*

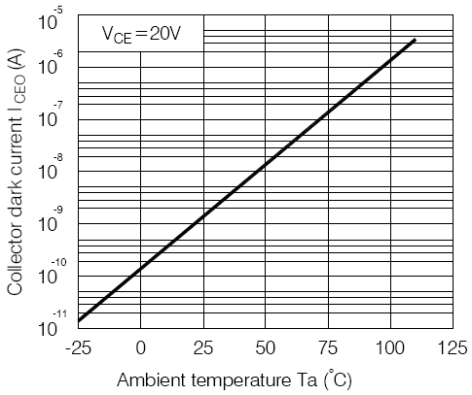


Figure 10: *Response Times vs. Load Resistance (R_L)*

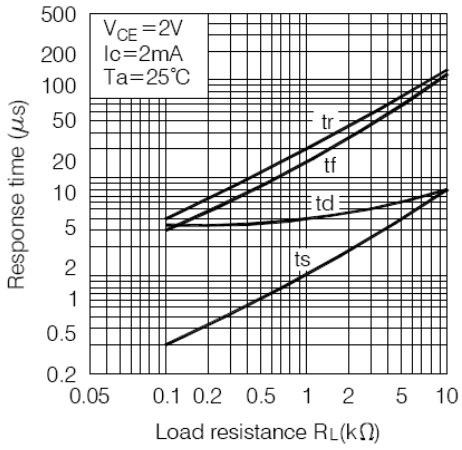
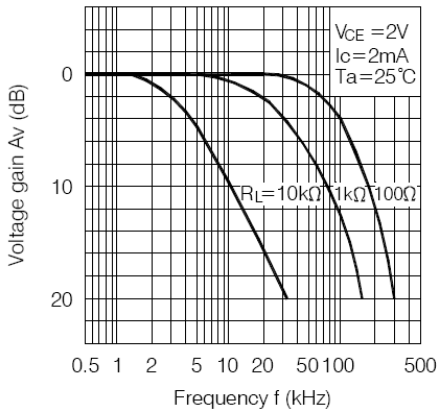


Figure 11: *Frequency Response Characteristics*

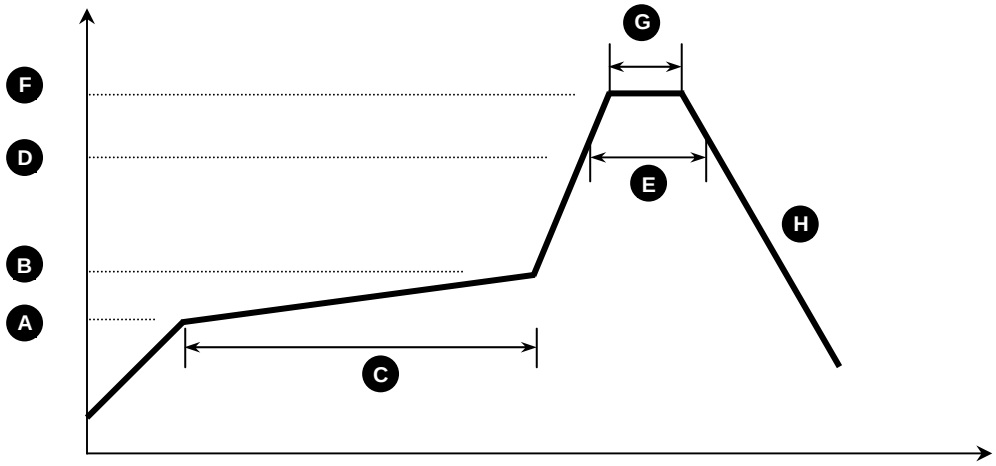


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SDT800 Solder Reflow Temperature Profile Recommendations

(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250ºC:



Process Step	Description	Parameter
A	Preheat Start Temperature (ºC)	150ºC
B	Preheat Finish Temperature (ºC)	180ºC
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (ºC)	230ºC
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (ºC)	260ºC
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (ºC/s)	<6ºC/s

(2) *Wave Solder:*

Maximum Temperature:	260ºC (at terminal)
Maximum Time:	10s
Pre-heating:	100 - 150ºC (30 - 90s)
Single Occurrence	

(3) *Hand Solder:*

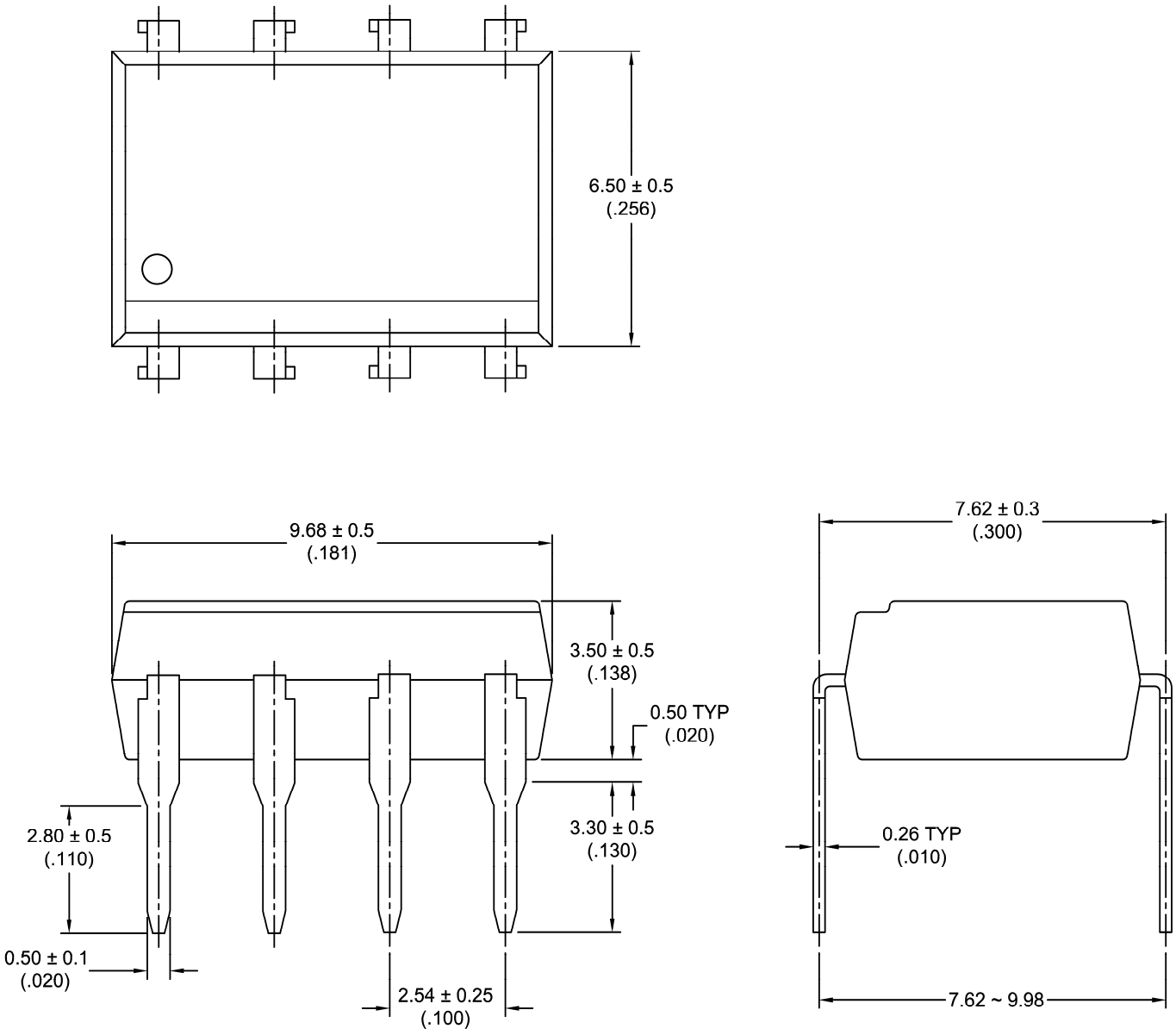
Maximum Temperature:	350ºC (at tip of soldering iron)
Maximum Time:	3s
Single Occurrence	

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SDT800 Package Dimensions

8 PIN DIP Package

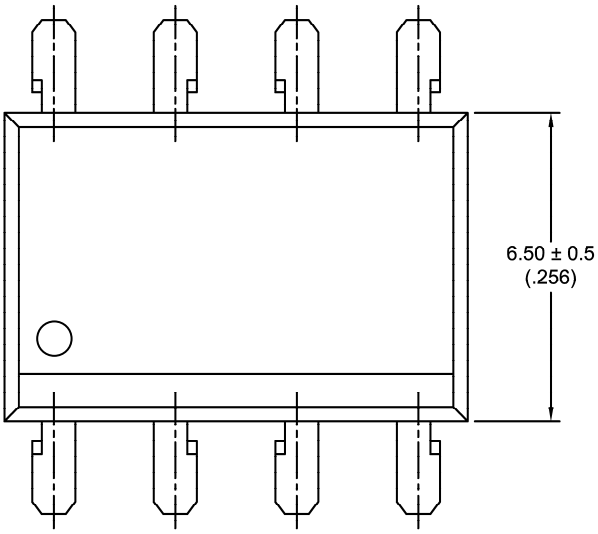
Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*

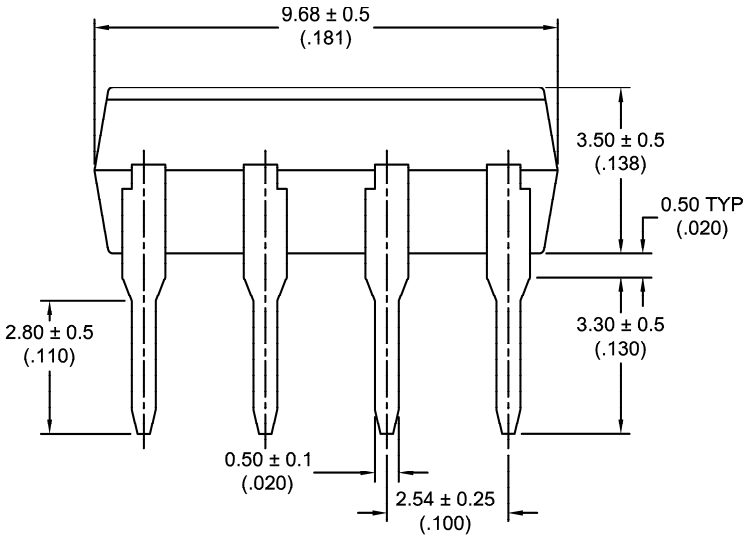


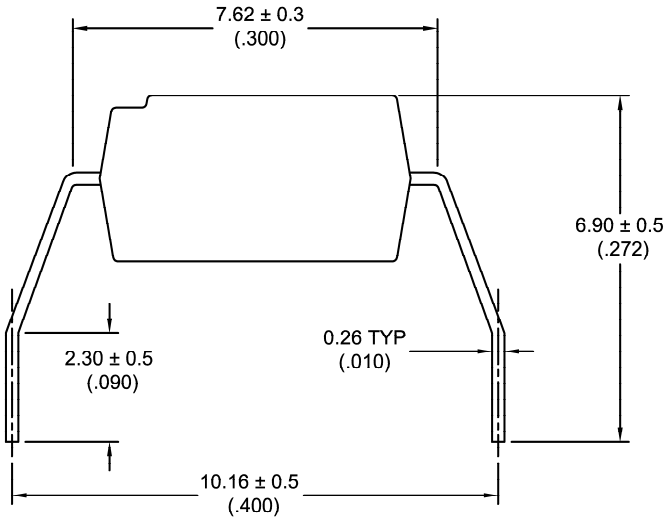
SDT800 Package Dimensions

8 PIN WIDE Lead Space Package (-H)

Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*



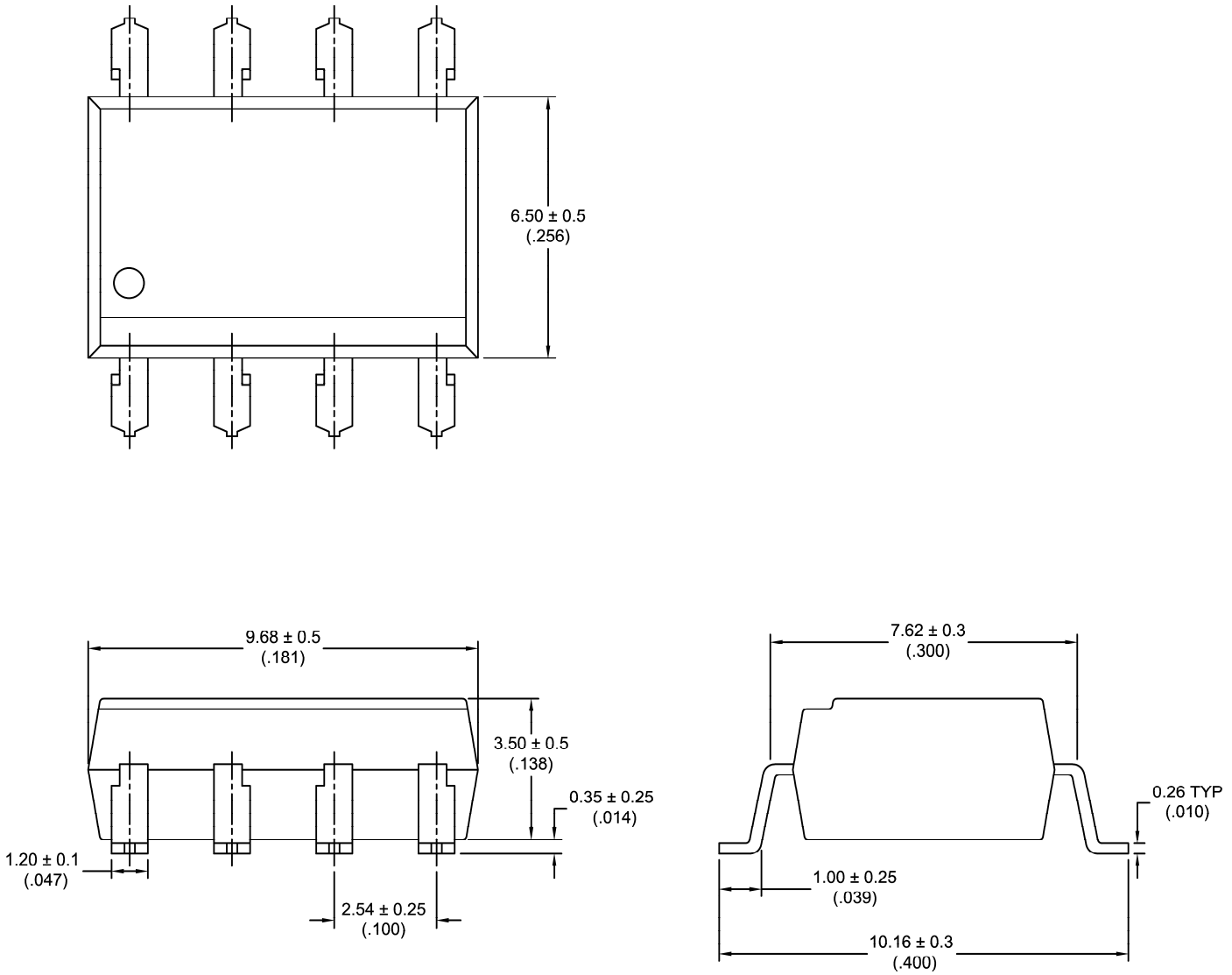




SDT800 Package Dimensions

8 PIN SMD Surface Mount Package (-S)

Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*

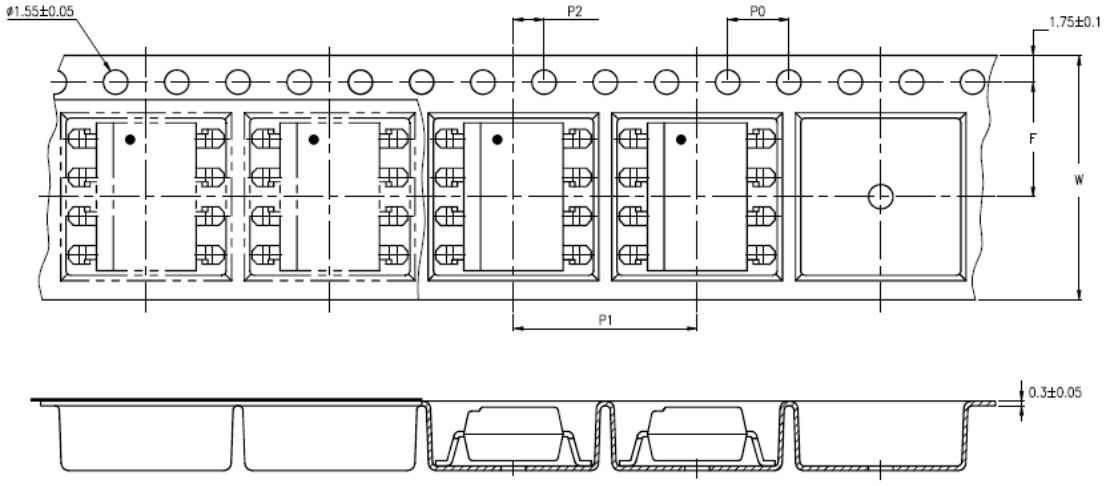


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SDT800 Packaging Specifications

Tape & Reel Specifications (T&R)

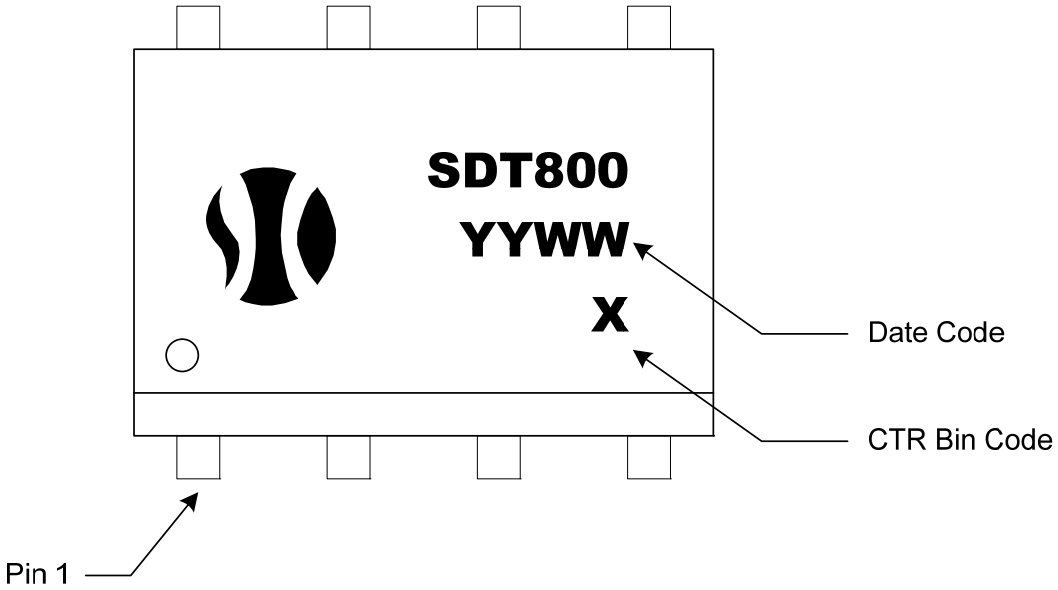
Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*



Specification	Symbol	Dimensions, mm (inches)
Tape Width	W	16 ± 0.3 (0.63)
Sprocket Hole Pitch	P0	4 ± 0.1 (0.15)
Compartment Location	F P2	7.5 ± 0.1 (0.295) 2 ± 0.1 (0.079)
Compartment Pitch	P1	12 ± 0.1 (0.472)

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SDT800 Packaging Marking



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